



Patent  
Attorney's Docket No. 016660-055

**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

In re Patent Application of	)	
	)	
Wing Cheung HO et al	)	Group Art Unit: 1725
	)	
Application No.: 09/649,084	)	Examiner: L. Edmondson
	)	
Filed: August 28, 2000	)	Confirmation No.: 7505
	)	
For: WIRE-BONDING APPARATUS	)	
WITH IMPROVED XY-TABLE	)	
ORIENTATION	)	

**AMENDMENT**

Assistant Commissioner for Patents  
Washington, D.C. 20231

Sir:

In response to the Office Action dated March 19, 2002, kindly amend the above-identified application as follows:

**IN THE CLAIMS:**

1. (Thrice Amended) Wedge wire bonding apparatus comprising:
  - (a) means for supporting a workpiece,
  - (b) a bonding head including a transducer having a longitudinal axis,
  - (c) means for causing relative movement of the workpiece and the transducer along an X axis,
  - (d) means for causing relative movement of the workpiece and the transducer along a Y axis orthogonal to said X axis, and

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